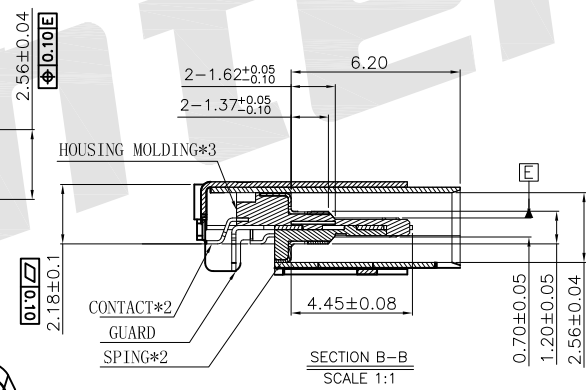
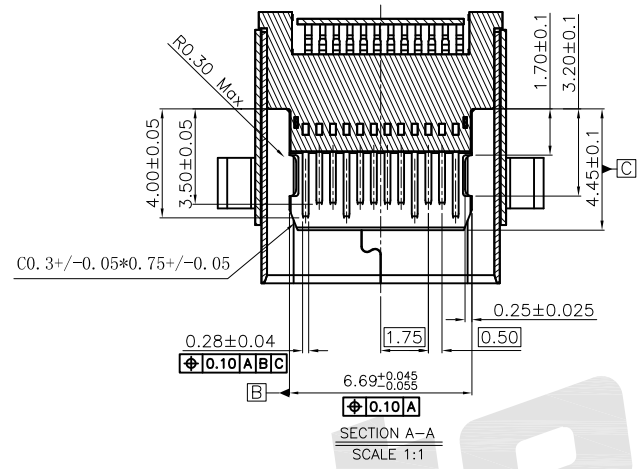
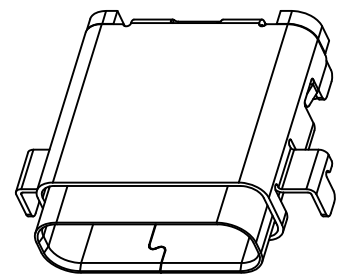
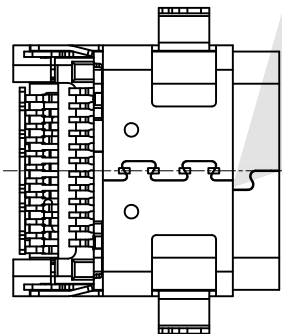
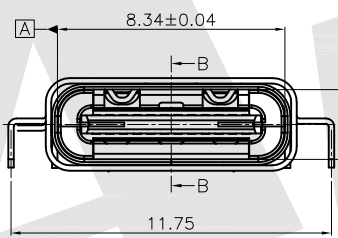
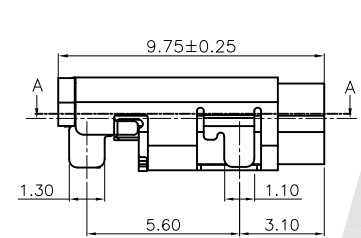
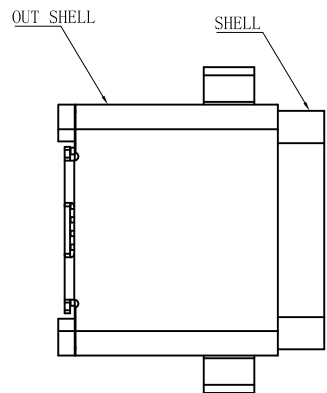


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Specifications:

Electical:

1. Contact Resistance : 20 Milliohm Max.
2. Dielectric Withstanding Voltage: 100V AC AT Sea Level
3. Insulation Resistance: 100 Megohms Min.

Material:

1. Housing: LCP, Glass Fiber Filled, Black
2. Contact: Brass (t=0.12mm).
3. Guard Plate: Stainless Steel, T=0.10mm
4. Shield: Stainless Steel (t=0.30mm).

Finish:

1. Contact : 30u" Gold Plating On Contact Area
120u" Min. Tin(Matte) Plating On Solder tails
Area 80u" Min. Nickel Underplating Over All
2. Shell: Plated Nickel Plating

Mechanical:

1. Mating Force: 5-20N Max.
2. Unmating Force: 8-20N Min.
3. Durability: 10000 Cycles

U3. 1FM01 - S - L - X - X - X

- | | | | | | |
|--------------|-------------------|-----------------------|---------------------|-------------------|-------------|
| ① | ② | ③ | ④ | ⑤ | ⑥ |
| ① Series No: | ② Shell Material: | ③ Insulator Material: | ④ Contact Material: | ⑤ Contact Plating | ⑥ Packing |
| | S:stainless steel | L:LCP | B:Brass | G0: Gold flash | A:Tray |
| | | | P:phosphor copper | G1: 3u" Gold | B:Bag |
| | | | | G2: 5u" Gold | C:Tube |
| | | | | G3: 10u" Gold | D:Tape&Reel |
| | | | | G4: 15u" Gold | |
| | | | | G5: 30u" Gold | |

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
DRAW Ly Xun Hua DATE 27/06/2019
CHECK BobYang DATE 27/06/2019

Antenk ANTEK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail:sales@antenk.com

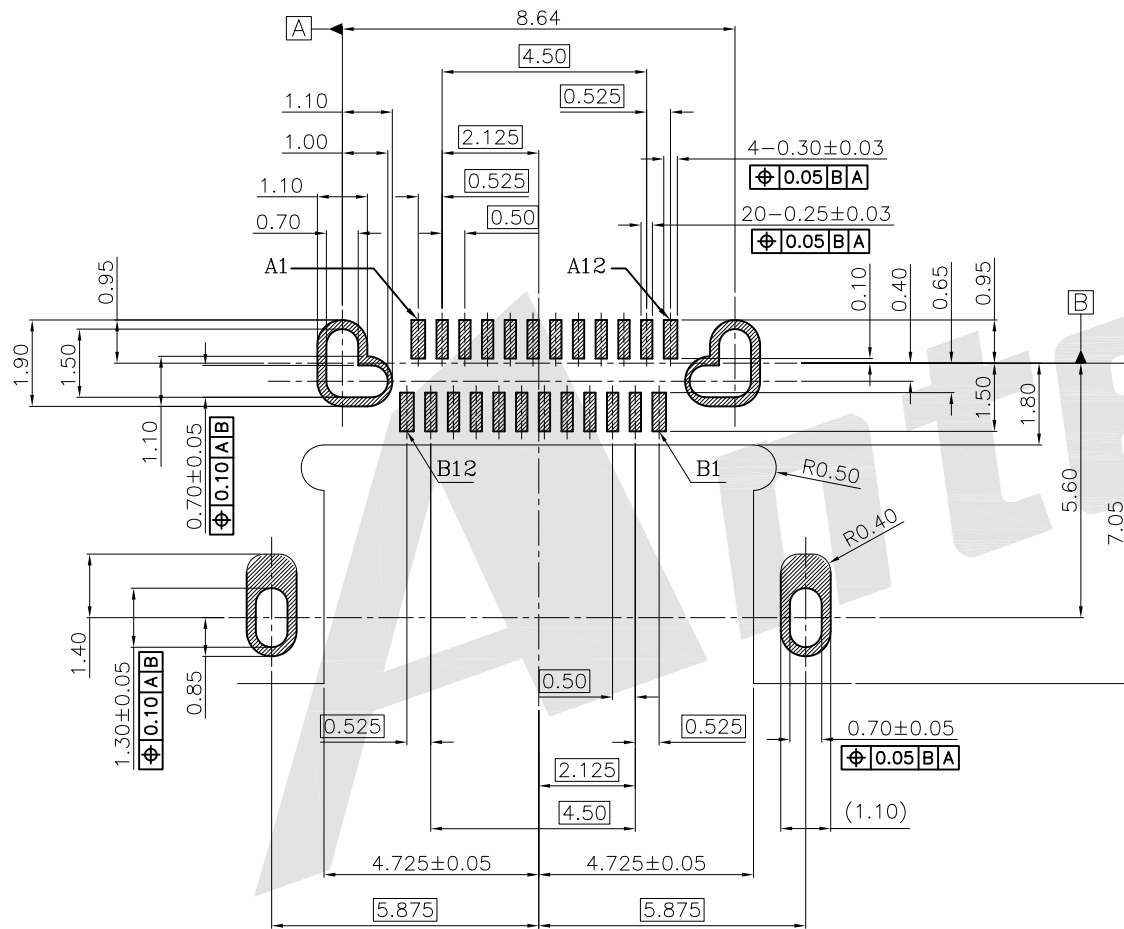
TITLE: USB3.1 Receptacle C Type SMT

DRAWING NO: U3. 1FM01-SLXXX
PRODUCT NO: U3. 1FM01-SLXXX



REV	DESCRIPTION	DATE
1		

HSF



USB TYPE-C FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS

PIN	Signal Name	Description	PIN	Signal Name	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of first SuperSpeed RX differential pair
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of first SuperSpeed RX differential pair
A4	Vbus	Bus Power	B9	Vbus	Bus Power
A5	CC1	Configuration Channel	B8	SBU2	Sideband Use (SBU)
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A8	SBU1	Sideband Use (SBU)	B5	CC2	Configuration Channel
A9	Vbus	Bus Power	B4	Vbus	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B3	SSTXn2	Negative half of second SuperSpeed TX differential pair
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B2	SSTXp2	Positive half of second SuperSpeed TX differential pair
A12	GND	Ground return	B1	GND	Ground return

RECOMMEND PCB LAYOUT
(THICKNESS: 1.00 OR 1.20mm)

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
DRAW Ly Xun Hua DATE 27/06/2019
CHECK BobYang DATE 27/06/2019

Antenk ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE: USB3.1 Receptacle C Type SMT

DRAWING NO: U3.1FM01-SLXXX

PRODUCT NO: U3.1FM01-SLXXX



REV	DESCRIPTION	DATE
1		